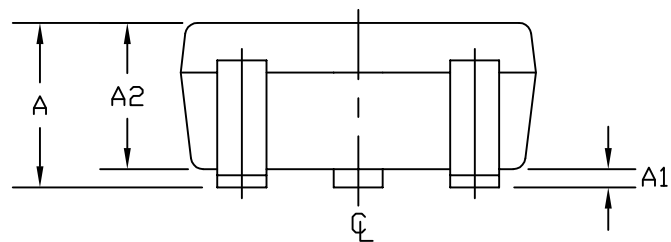



SYMBOL	MIN	NOM	MAX
A	0.90	1.25	1.45
A1	0.00	0.05	0.15
A2	0.90	1.10	1.30
b	0.35	0.40	0.50
C	0.08	0.15	0.20
D	2.80	2.90	3.00
E	2.60	2.80	3.00
E1	1.50	1.625	1.75
L	0.35	0.45	0.60
L1	0.60 REF		
e	0.95 BSC.		
e1	1.90 BSC.		
alpha	0°	2.5°	8°
PKG CODES: U5-1, U5-2			



NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS.
-  FOOT LENGTH MEASURED AT INTERCEPT POINT BETWEEN DATUM A & LEAD SURFACE.
- PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASH & METAL BURR. MOLD FLASH, PROTRUSION OR METAL BURR SHOULD NOT EXCEED 0.25 MM.
- PACKAGE OUTLINE INCLUSIVE OF SOLDER PLATING.
- MEETS JEDEC MO178, VARIATION AA.
- LEADS TO BE COPLANAR WITHIN 0.10 mm.
- SOLDER THICKNESS MEASURED AT FLAT SECTION OF LEAD BETWEEN 0.08mm AND 0.15mm FROM LEAD TIP.

**DALLAS SEMICONDUCTOR** **MAXIM**  
 PROPRIETARY INFORMATION  
 TITLE: PACKAGE OUTLINE, SOT-23, 5L  
 APPROVAL: \_\_\_\_\_ DOCUMENT CONTROL NO. 21-0057 REV. F 1/1